L Number	Hits	Search Text	DB	Time stamp
-	27	etch\$3 same (interlayer interlevel	USPAT;	2002/03/14 12:23
		intermediate) same (organic teflon	US-PGPUB; EPO; JPO;	
		polyaryl\$6 poly\$1para\$1xylene) same (NH3	DERWENT;	
		"NH.sub.3" ammonia)	IBM TDB	
İ	2200	etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 13:02
-	2300	intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
-		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)	IBM TDB	
_	613	(etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 12:22
		intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM_TDB	1
		intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))		
	350		USPAT;	2002/03/14 12:22
-	350	intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	2002, 00, 21 22122
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM TDB	
		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))		0000/00/14 10 00
-	925		USPAT;	2002/03/14 12:23
		intermediate) and (organic teflon polyary1\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO; DERWENT;	
		ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel	IBM TDB	
		intermediate) near insulat\$3) not (etch\$3	1011_100	
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
i		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia)))		
_	289		USPAT;	2002/03/14 12:23
-	209	intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	2002,00,11 22:00
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM_TDB	
		intermediate) near insulat\$3) not (etch\$3	_	
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
į		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
1		polyary1\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		portyrparagrafactor dame (into introduct	i	I
ŀ		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		

-	184	((((etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 12:23
		intermediate) and (organic teflon polyary1\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM TDB	
		intermediate) near insulat\$3) not (etch\$3	12.1_122	
		intermediate) hear insulates) not (etches)		
		same (interlayer interlevel intermediate)		1
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		Ì
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		
	1	same (interlayer interlevel intermediate)		
	1	same (interrayer interrever intermediate)		
		same (organic teflon polyary1\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
•		ammonia)) and etch\$3 with (NH3 "NH.sub.3"		
		ammonia)		
_	37		USPAT;	2002/03/14 12:24
[intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
1		ammonia) and (plasma merie RIE dry adj	DERWENT;	,
	1	ammonia, and (prasma metre are dry adj	IBM TDB	
		etch\$3)) and ((interlayer interlevel	1 100 100	
		intermediate) near insulat\$3) not (etch\$3		
,		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon	}	
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		1
	İ	dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		
		intermediate) hear dielectric, not (etchys		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
	1	poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
		ammonia)) and etch\$3 with (NH3 "NH.sub.3"		
		ammonia)) and (interlayer interlevel		ŀ
		intermediate) with (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene)		
	780		USPAT;	2002/03/14 13:03
_	780	intermediate) and (organic teflon polyaryl\$6	IIS-PGPIIB:	,
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		polystpatastxytene, and (Nns "Nn. Sub. 3"		
	1	ammonia) and (plasma merie RIE dry adj	DERWENT;	1
		etch\$3)) and (NH3 "NH.sub.3" ammonia) same	IBM_TDB	1
		(plasma merie RIE dry adj etch\$3)		0000/00/0
-	430	(((etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 13:04
		intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	
	1	poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM TDB	
		intermediate) near insulat\$3) not (etch\$3		1
	1			
1		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
1		ammonia))) ((etch\$3 and (interlayer		
İ		interlevel intermediate) and (organic teflon	1	
1	1	polyaryl\$6 poly\$1para\$1xylene) and (NH3		
	1	"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		İ
1		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
1		same (organic teflon polyaryl\$6		1
1		poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia)))) and (NH3 "NH.sub.3" ammonia)		
1		I SMMODIALI II ADD INHK "NH SUD K" AMMODIA)	1	The state of the s
		same (plasma merie RIE dry adj etch\$3)		

	212	(((etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 13:05
-	313	intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
1		etch\$3)) and ((interlayer interlevel	IBM TDB	
		intermediate) near insulat\$3) not (etch\$3	1511_155	1
		intermediate) near insuraces; not (ecches		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6]
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		İ
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		1
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and (NH3 "NH.sub.3" ammonia)		
		with (plasma merie RIE dry adj etch\$3)	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	2002/02/24 22 25
-	63	(((((etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 13:05
		intermediate) and (organic teflon polyary1\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM_TDB	
		intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
		ammonia)) and etch\$3 with (NH3 "NH.sub.3"		
		ammonia)) and ((((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
		polyary1\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyary1\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
		polyary1\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
1		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		-
		ammonia)))) and (NH3 "NH.sub.3" ammonia)		1
1	1	with (plasma merie RIE dry adj etch\$3))		

-	43	(((((etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 13:05
		intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
	İ	ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM_TDB	
		intermediate) near insulat\$3) not (etch\$3		
	}	same (interlayer interlevel intermediate)		
		same (organic teflon polyary1\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon		
		polyary1\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
		ammonia)) and etch\$3 with (NH3 "NH.sub.3"		
		ammonia)) and ((((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
-		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
	1	intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate)		
-		same (organic teflon polyaryl\$6		1
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
1		intermediate) near dielectric) not (etch\$3		†
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and (NH3 "NH.sub.3" ammonia)		
		with (plasma merie RIE dry adj etch\$3))) not		
		(((((etch\$3 and (interlayer interlevel		
i		intermediate) and (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"		
-		ammonia) and (plasma merie RIE dry adj		
1		etch\$3)) and ((interlayer interlevel		
		intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
]		ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
		ammonia)) and etch\$3 with (NH3 "NH.sub.3"		
		ammonia)) and (interlayer interlevel		
		intermediate) with (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene))		
-	25		USPAT;	2004/06/27 09:33
		dissolv\$3) near (photoresist resist) with	US-PGPUB;	
] 1		((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with	EPO; JPO;	
		(HF fluori?e) with (peroxide H2o2 "H.sub.2	DERWENT; IBM TDB	
		0.sub.2"))	מעד זיום ד	<u> </u>

-	64	(strip\$4 remov\$3 etch\$3 clean\$3 develop\$3	USPAT;	2004/06/27 08:45
	!	dissolv\$3) with (photoresist resist) same ((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with	US-PGPUB; EPO; JPO;	
		(H2SO4 "H.sub.2 SO.sub.4" suffuric) with (HF fluori?e) with (peroxide H2o2 "H.sub.2	DERWENT;	
		O.sub.2"))	IBM TDB	
	39	((strip\$4 remov\$3 etch\$3 clean\$3 develop\$3	USPAT;	2004/06/27 08:53
	39	dissolv\$3) with (photoresist resist) same	US-PGPUB;	
		((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with	EPO; JPO;	
		(HF fluori?e) with (peroxide H2o2 "H.sub.2	DERWENT;	
		O.sub.2"))) not ((strip\$4 remov\$3 etch\$3	IBM_TDB	
		clean\$3 develop\$3 dissolv\$3) near		
		(photoresist resist) with ((H2SO4 "H.sub.2		
		SO.sub.4" sulfuric) with (HF fluori?e) with	. 1	
		(peroxide H2o2 "H.sub.2 O.sub.2")))	HCDATE.	2004/06/27 08:47
-	38	(("5266157") or ("6352937") or ("6033996")	USPAT; US-PGPUB;	2004/06/2/ 08:4/
		or ("5384649") or ("5584740") or ("6153484") or ("3944421") or ("4883541") or ("5300463")	EPO; JPO;	
		or ("3944421") or ("4883541") or ("5300463") or ("5985125") or ("5824419") or ("5830280")	DERWENT;	
		or ("5250958") or ("6124211") or ("6046115")	IBM TDB	
		or ("6030879") or ("5776817") or ("5716495")		
		or ("5296093")).PN.		
_	19	1	USPAT	2004/06/27 08:47
		or ("5384649") or ("5584740") or ("6153484")		
		or ("3944421") or ("4883541") or ("5300463")		
		or ("5985125") or ("5824419") or ("5830280")		
		or ("5250958") or ("6124211") or ("6046115")		
		or ("6030879") or ("5776817") or ("5716495")		
		or ("5296093")).PN.		2004/06/27 00:22
-	58	(((strip\$4 remov\$3 etch\$3 clean\$3 develop\$3	USPAT; US-PGPUB;	2004/06/27 09:32
		dissolv\$3) with (photoresist resist) same ((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with	EPO; JPO;	
		(H2SO4 "H.Sub.2 So.Sub.4" Suffuric) with (H2SO4 "H.Sub.2 Sub.4" Suffurice with (H2SO4 "H.Sub.2 Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Suffurice with Sub.4" Sub.4" Suffurice with Sub.4" S	DERWENT;	
		O.sub.2"))) ((("5266157") or ("6352937") or	IBM TDB	
		("6033996") or ("5384649") or ("5584740") or		
ļ		("6153484") or ("3944421") or ("4883541") or		
		("5300463") or ("5985125") or ("5824419") or		
		("5830280") or ("5250958") or ("6124211") or		*
		("6046115") or ("6030879") or ("5776817") or		
		("5716495") or ("5296093")).PN.)) not		
		((strip\$4 remov\$3 etch\$3 clean\$3 develop\$3		
		dissolv\$3) near (photoresist resist) with		
		((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with		
		(HF fluori?e) with (peroxide H2o2 "H.sub.2		
		0.sub.2")))	USPAT	2004/06/27 08:49
	10	20040016719.URPN. (US-5996424-\$ or US-5266157-\$ or	USPAT;	2004/06/27 09:32
-	10	US-5326490-\$ or US-5185154-\$ or US-4883541-\$	DERWENT	
		or US-4585515-\$ or US-5804744-\$ or		
		US-5863828-\$ or US-6352937-\$).did. or	1	
		(JP-05013920-\$).did.		
-	6	(US-5605602-\$ or US-5589077-\$ or	USPAT;	2004/06/27 09:33
		US-6225424-\$ or US-6417510-\$ or	US-PGPUB	
		US-6509686-\$).did. or		
		(US-20010037979-\$).did.	HODAM.	2004/06/27 09:33
-	16		USPAT;	2004/00/2/ 09:33
		US-5326490-\$ or US-5185154-\$ or US-4883541-\$ or US-4585515-\$ or US-5804744-\$ or	US-PGPUB; EPO; JPO;	
		US-5863828-\$ or US-6352937-\$).did. or	DERWENT;	
1		(JP-05013920-\$).did.) ((US-5605602-\$ or	IBM TDB	
		US-5589077-\$ or US-6225424-\$ or US-6417510-\$		
		or US-6509686-\$).did. or		
		(US-20010037979-\$).did.)		
_	4	1	USPAT	2004/06/27 19:03
		or ("5895563")).PN.		
-	0		EPO	2004/06/27 19:03
-	2	"618612" "346668"	EPO	2004/06/27 19:21